



Evyap Sabun Malaysia Sdn Bhd

Evyap Oleo O-1872

Oleic Acid 72 %

Product Data Sheet

CAS No. 67701-08-0

EINECS No. 266-932-7

Parameter	Unit	Specification
Appearance at 30 Deg. C	-	Pale yellow liquid, free of foreign matter
Colour, Lovibond, Max	In 5,1/4" Cell	Y=8.0; R=1.0
Acid Value	mg KOH/Gm	195-205
Sap. Value	mg KOH/Gm	196-206
Iodine Value	Gms I2 / 100 Gms	86.0 Min
Cloud Point	° C	20.0 Max

Fatty Acid Composition	Unit	Specification
C16:0 & below	% by GC	3.0 Max
C18 :0	% by GC	6.0 Max
C 18:1	% by GC	72.0 Min
C 18:2	% by GC	20.0 Max
Others	% by GC	1.0 Max

The above chart indicates typical available specifications. Customised specifications are also available.

APPLICATIONS

Food ingredients, esters, surfactants, transparent soaps, cosmetics and personal care products. Lubricants, metallic soaps, coatings and adhesives.

PACKING

Available in standard 180kg MS/HDPE drums, IBC containers or flexi bags, Bulk ISO container loads. Customised packing size can be made available upon request.

BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

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